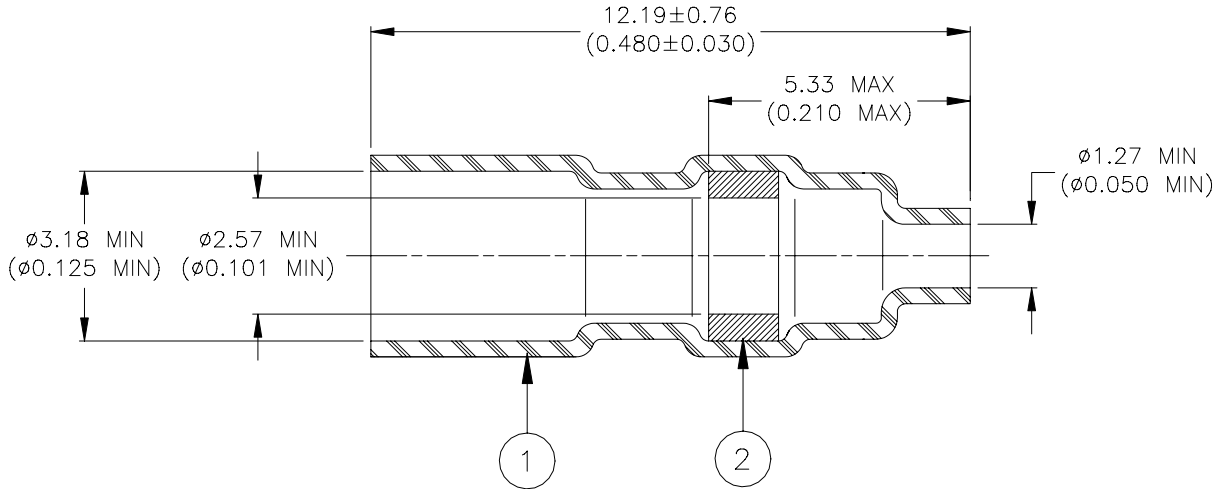


SPECIFICATION CONTROL DRAWING



MATERIALS

1. INSULATION SLEEVE: Heat shrinkable, transparent blue, radiation cross-linked polyvinylidene fluoride.
2. SOLDER PREFORM WITH FLUX:
 SOLDER: TYPE Sn63 per ANSI J-STD-006.
 FLUX: TYPE ROL1 per ANSI J-STD-004.

APPLICATION

1. This part is designed for connecting pre-tinned leads to pre-tinned terminal pins having diameters from 0.64 to 1.27 (0.025 to 0.050) and a height of 5.08 to 5.72 (0.200 to 0.225).
2. Part will satisfactorily solder assemblies having a total cross-sectional area of 1800 to 4500 circular mils. Total circular mil area = Sum of the squares of the component diameters. Not more than 3 leads shall be attached to one terminal pin.
3. Tubing will recover to 1.27 (0.050) I.D. max.
4. Temperature rating: -65°C to +150°C.
5. For assembly technique, see sheet 2.

tyco / Electronics / Raychem 307 Constitution Drive Menlo Park, CA 94025, USA		Wire and Harnessing Products	TITLE: SOLDERSLEEVE, PIN CONTACT Pin Contact 0.64 to 1.27 (0.025 to 0.050) Diameters				
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS. INCHES DIMENSIONS ARE BETWEEN BRACKETS.			DOCUMENT NO.: D-141-25				
TOLERANCES: 0.00 N/A 0.0 N/A 0 N/A	ANGLES: N/A ROUGHNESS IN MICRON	Tyco Electronics reserves the right to amend this drawing at any time. Users should evaluate the suitability of the product for their application.	DCR NUMBER: D010065		REPLACES: N/A		
DRAWN BY: M. FORONDA	DATE: 04-Apr.-01	PROD. REV. C	DOC ISSUE: 1	SCALE: None	SIZE: A	SHEET: 1 of 2	

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SPECIFICATION CONTROL DRAWING

THERMOFIT ASSEMBLY PROCEDURE

1. LEAD PREPARATION


- a) Strip 4.75 to 5.54 (0.187 to 0.218) of insulation from end of lead(s) to be connected.
- b) Pre-tin leads to a length equal to the total strip length minus the outside diameter of the wire insulation.

2. TERMINAL PREPARATION

- a) Terminals to be soldered shall be cleaned with a non-corrosive material such as trichlorethylene and dried with a clean, lint-free wiper.
- b) If devices have not been supplied with pre-tinned terminals, said terminals shall be pre-tinned to within 1.27 (0.050) of the body of the device with Sn63 solder.

3. ASSEMBLY PROCEDURE

- a) Place solder sleeves over one row of the terminals to be soldered.
- b) Place back reflector behind row of sleeves. A piece of 1.60 (1/16 inch) sheet metal at least 15.88 (5/8 inch) high and extending the full length of the row of solder sleeves is suitable for this purpose.
- c) Insert stripped ends of leads into sleeve so that they bottom against the internal ledge at the base of the sleeve.
- d) Secure leads into a suitable wire holding fixture.
- e) Apply heat until solder ring melts and flows. Heat should be applied with a Raychem shop air heater, Model CV-4504, equipped with a 991230 nozzle and operated at 6 - 8 psi. Nozzle should be held approximately one-quarter inch from sleeves. Heat should be applied to one sleeve at a time.

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